

# New Results on Opto-Electronics

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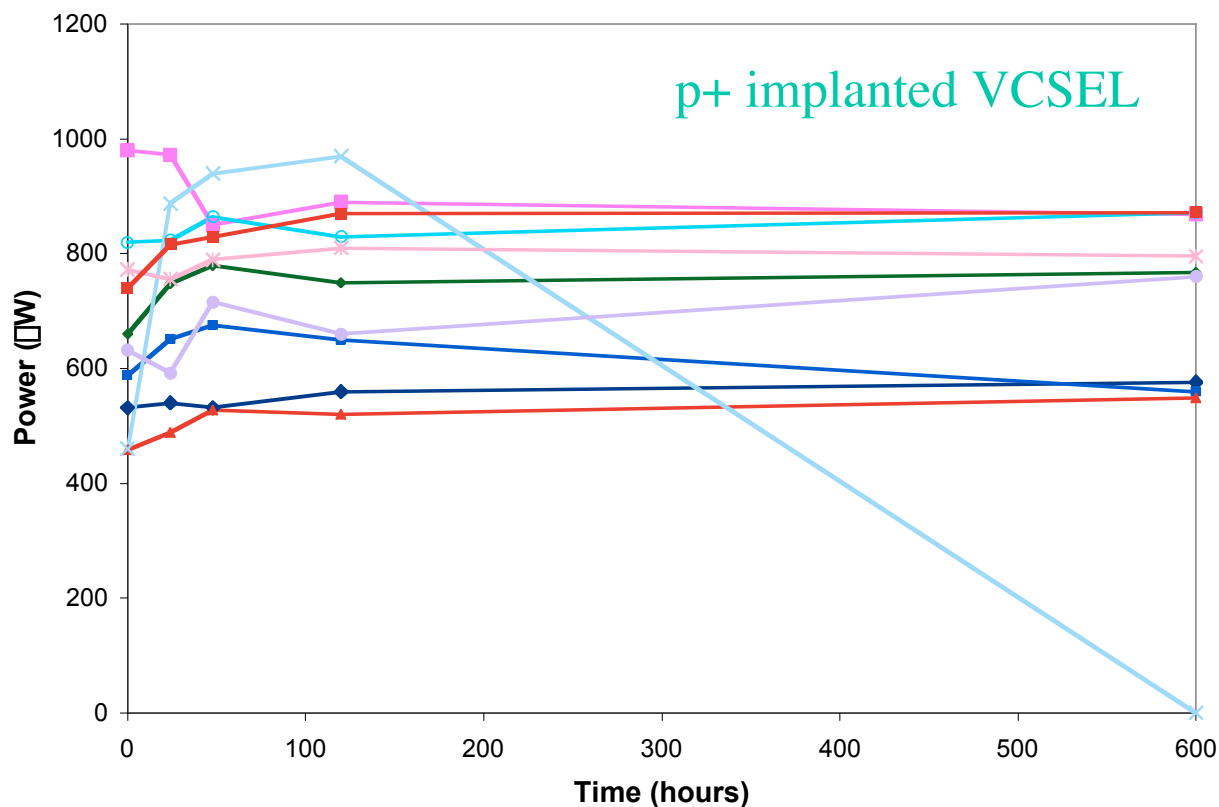
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A. Rahimi, C Rush, R. Ter-Antonian, M. Zoeller  
The Ohio State University

A. Ciliox, M. Holder, M. Ziolkowski  
Siegen University

# Outline

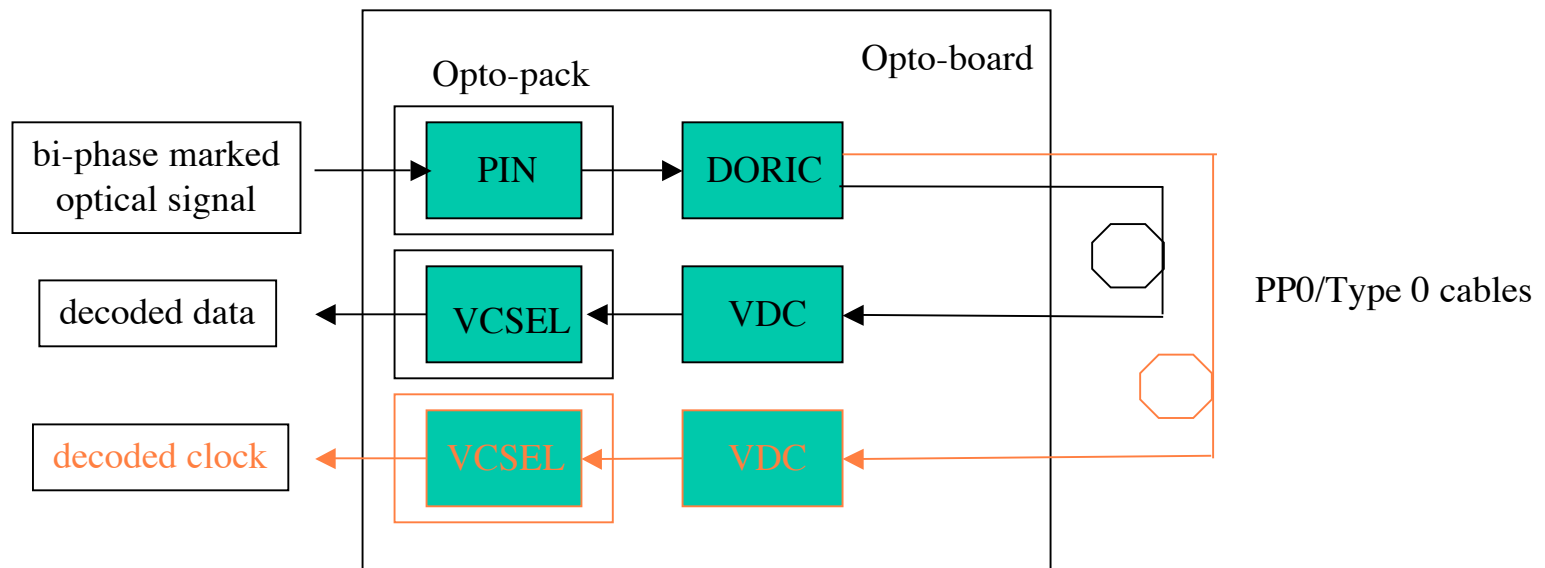
- Result on VCSEL Annealing
- Test with Type 0 cable
- Test with RX/TX
- Summary

# Optical Power of Irradiated Opto-boards after Annealing



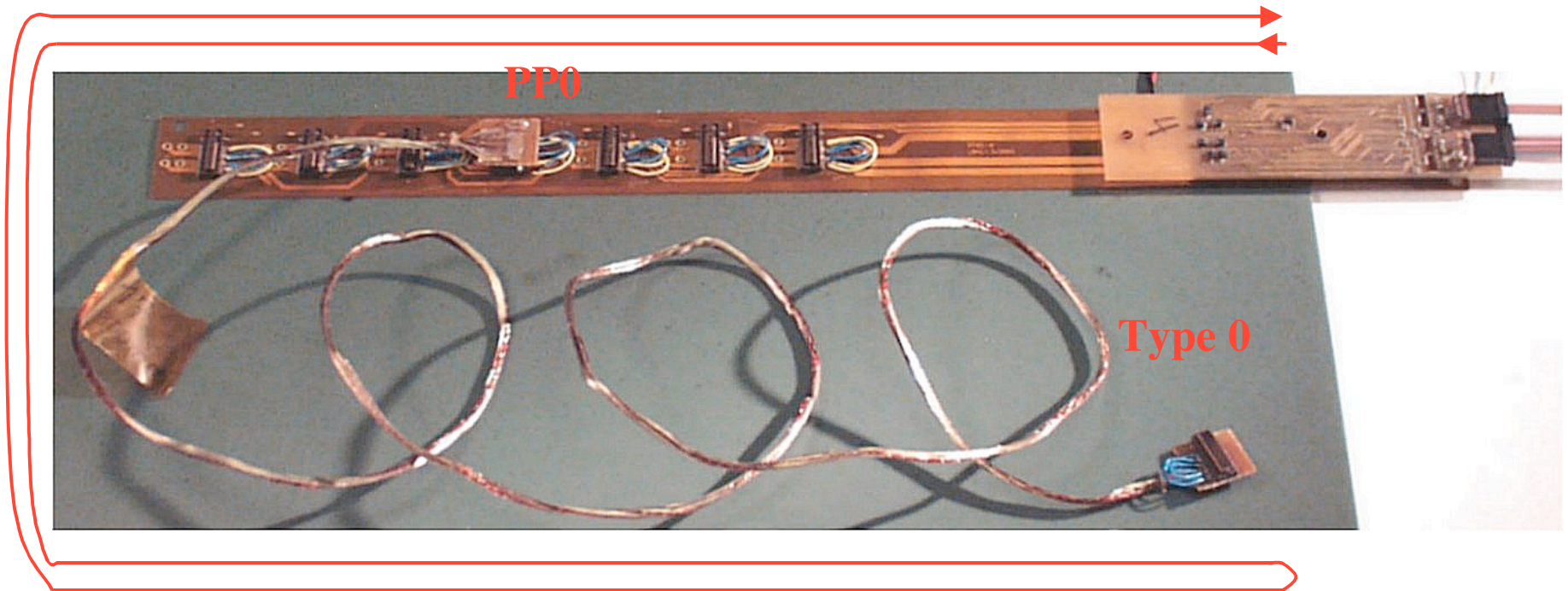
- limited annealing during irradiation partially recovers optical power lost
  - ⇒ all links have good optical power before annealing
- one VCSEL has large radiation damage
  - ⇒ large improvement with annealing
  - ⇒ dead after > 100 hours of annealing

# Bit Error Testing with PP0/Type 0 Cables



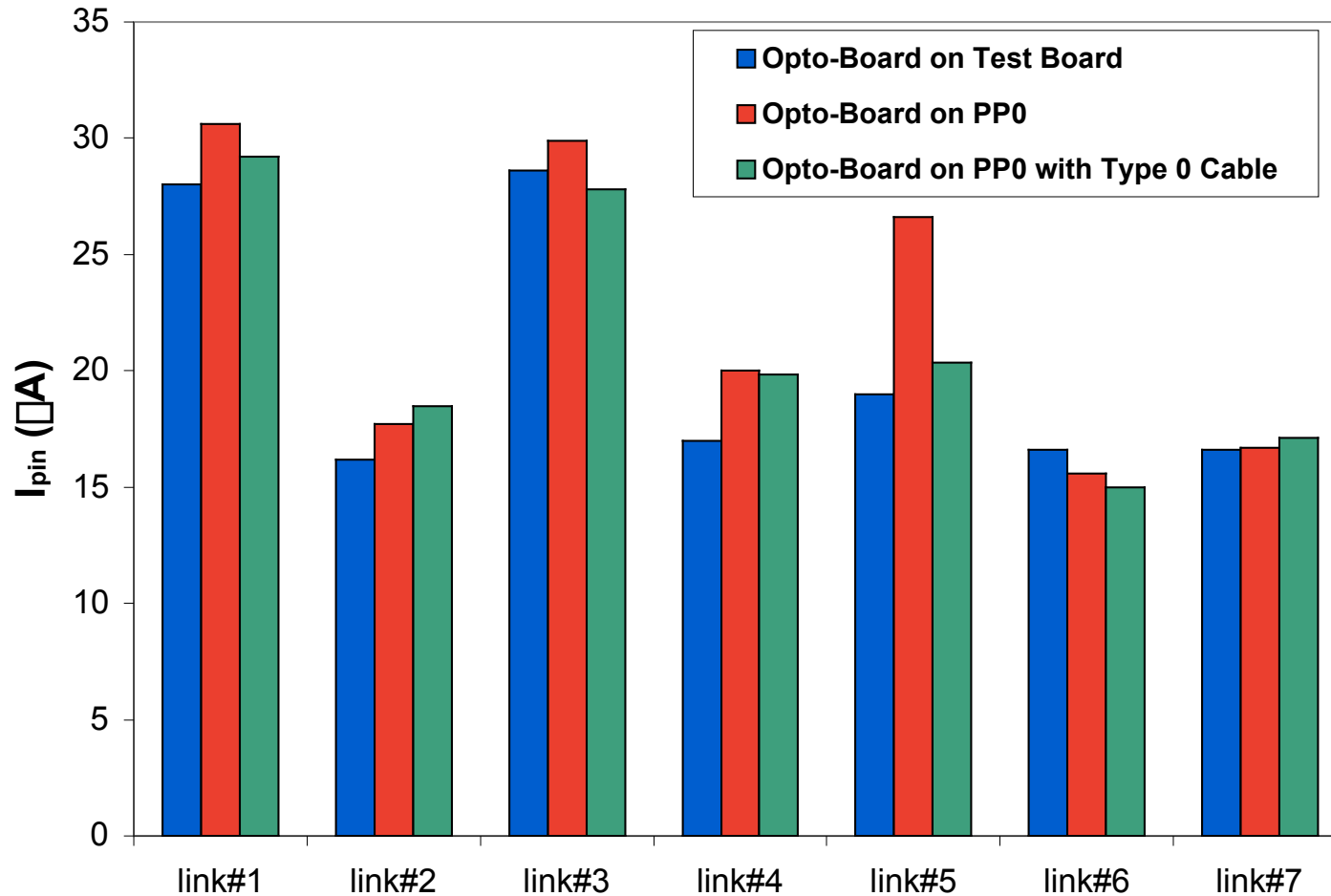
- compare original and decoded data  
⇒ measure minimum PIN current for no bit errors

# Opto-Board with PP0 + Type 0 Cables



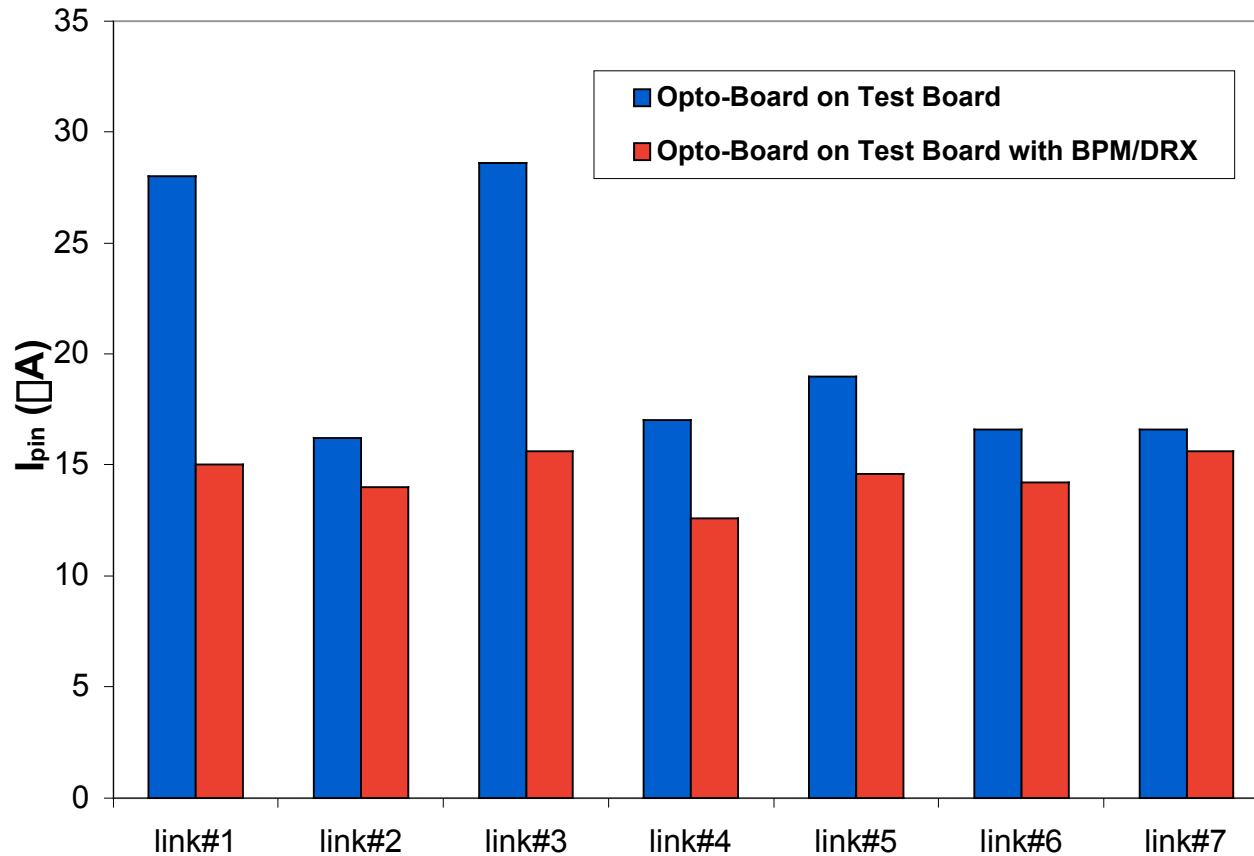
- data/clock from DORIC to VDC rerouted via PP0/Type 0 cables

# PIN Current Thresholds with PP0/Type 0 Cables



- PIN current thresholds measured with other links running at 40 mA
- no increase in thresholds with PP0/Type 0 cables

# PIN Current Thresholds with BPM/DRX



- thresholds for no bit error measured with other links running at 40 mA
- opto-board operates with lower thresholds with BPM/DRX
- ⇒ opto-board design is compatible with BPM/DRX

# Summary

- one irradiated VCSEL failed during annealing
- no change in PIN current thresholds for no bit errors with PP0/Type 0 cable
- lower PIN current thresholds with BPM/DRX
- ⇒ opto-board is compatible with BPM/DRX



# DORIC-I5e: Engineering Run

Presentation by Mike Zeoller

- **DORIC-I5e: March 2003, with MCC run**

3 metal layers (MPW runs), MZ top metal → 5 metals, LM top metal

⇒ improved power routing:

extra metals

LM sheet resistance is 61% that of MZ

⇒ reduced strays in input stage:

top metal shielding layer further separated from m1, m2

**Minor improvements:**

double # contacts in one preamp FET

⇒ max.  $\langle I_{PIN} \rangle$ : 2mA → 4mA

reduce area of input FET

⇒ reduce strays in input stage

Add power bypass capacitors (mimcaps?)